

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following amended Abstract of the Disclosure:

~~A chip-mounted substrate includes a chip electronic component on a ceramic substrate having surface electrodes. The chip electronic component includes a ceramic sintered compact defining an element assembly and terminal electrodes. The surface electrodes of the ceramic substrate are integrated with the corresponding external terminal electrodes by sintering.~~ A method for manufacturing a chip electronic component-mounted ceramic substrate includes the steps of mounting a chip electronic component including a ceramic sintered compact defining an element assembly and terminal electrodes on a ceramic green body having conductors thereon such that the terminal electrodes are brought into contact with the corresponding conductors, and firing the ceramic green body having the chip electronic component so as to integrate the conductors on the ceramic green body with the corresponding terminal electrodes of the chip electronic component by sintering.